

LTR.	ECN	DESCRIPTION	DATE	APP'D.

PIN TYPES
(SCALE 2X)

CHASSIS GROUND
(12X)



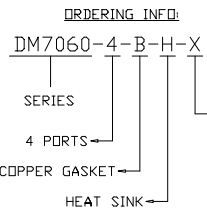
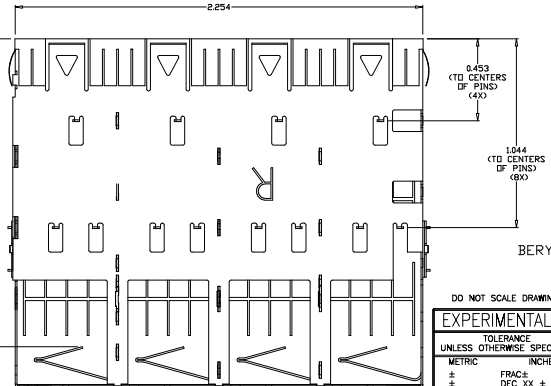
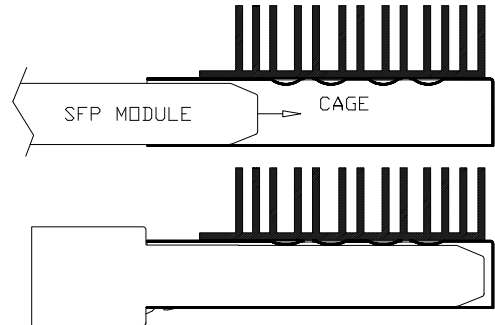
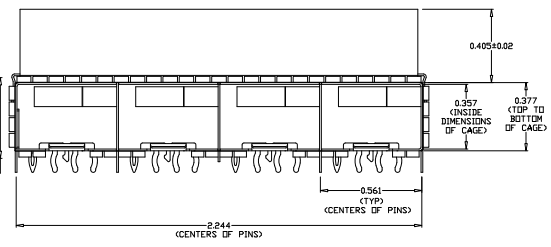
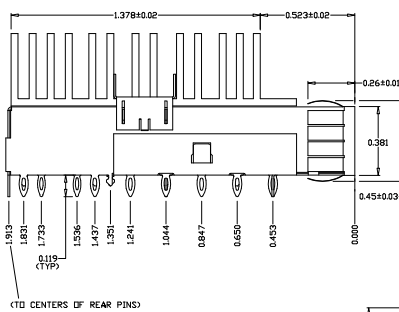
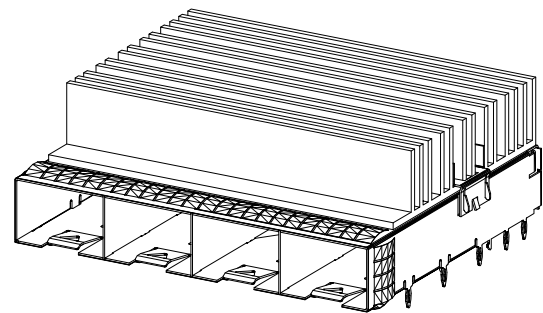
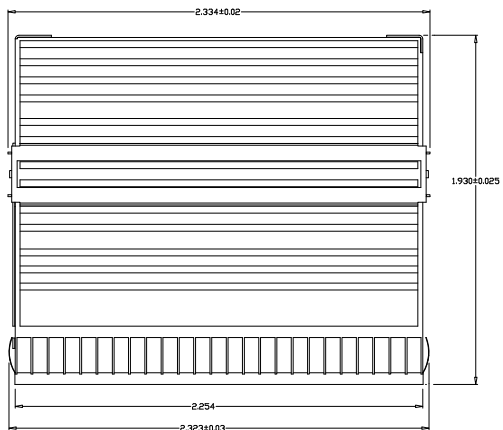
SMALL PIN
(8X)



LARGE PIN
(14X)



HALF LENGTH
(12X)



PLATING OPTIONS:

- R FOR 100µIN MATTE TIN OVER 50µIN NICKEL
NOT INTENDED FOR REFLOW
WAVE SOLDER ONLY - WAVE TEMP. 260°C FOR 6 SEC. MAX
RoHS COMPLIANT
- N FOR 60µIN NICKEL
CAGE IS REFLOW COMPATIBLE
MAX REFLOW TEMP. 260°C
RoHS COMPLIANT



DO NOT SCALE DRAWING.

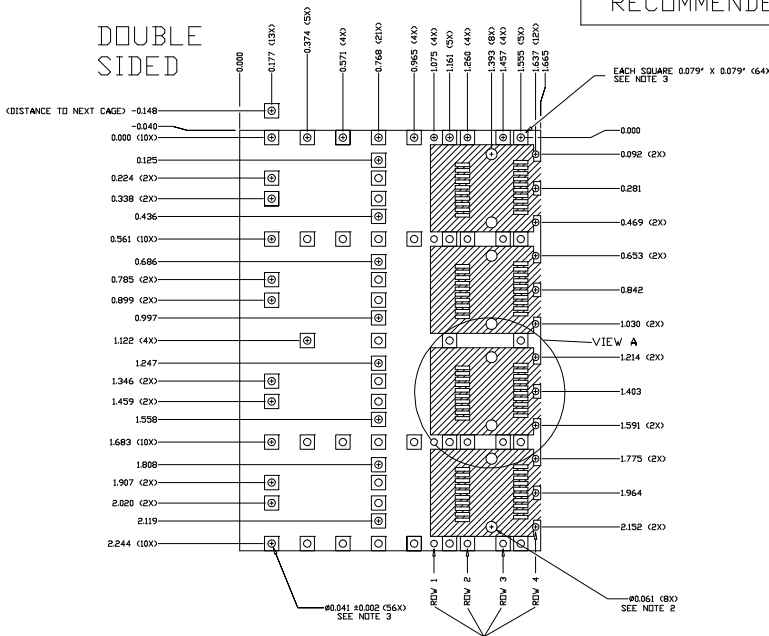
NOTES:

- 1) CAGE MATERIAL: 0.010" THICK BRASS ALLOY; C2680 - FULL HARD
- 2) GASKET MATERIAL: BERYLLIUM COPPER
PLATING FOR CAGE AND GASKETS: SEE ORDERING INFO
- 3) HEAT SINK MATERIAL: ALUMINUM
- 4) CLIP MATERIAL: COPPER ALLOY WITH NICKEL PLATING
- 5) OPERATING AND STORAGE TEMPERATURE: -40°C TO +160°C
- 6) CAGE IS SOLDERED AT SEAMS (LEAD FREE SOLDER)

EXPERIMENTAL NO:		DIVISION ASSIGNED: dataMate Division	
TOLERANCE UNLESS OTHERWISE SPECIFIED		DRAWN BY: DATE: 07/18/11	
METRIC ± DEC XX ± .010 ± ANGLES ± .005 TOOLING DIM (□) PART DWG (□) BREAK SHARP EDGES REMOVE ALL BURRS		CHECKED BY: J. LLORENS 07/18/11	
SEE NOTES		ENGR. APPROVAL: B. SKEPNEK 07/18/11	
SEE NOTES		APPROVED BY: A. CHIAPPETTA 07/18/11	
PART NO. CLASSIFICATION:		TITLE SFP+ EMI 4 PORT CAGE (MULTI-CONTACT) PRESS FIT PINS, HEAT SINK BERYLLIUM COPPER GASKET	
SIZE		CODE IDENT.	DWG. NUMBER
SCALE:		DM7060-4-B-H-X	
		Rev.	

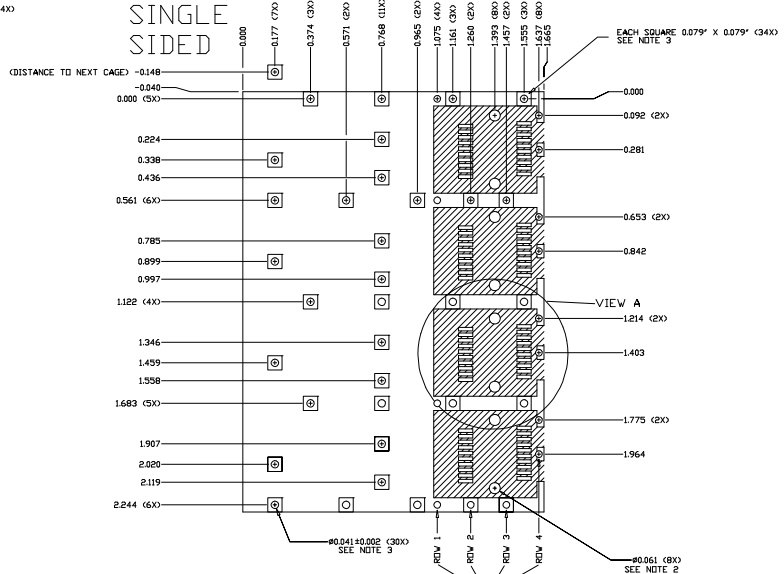
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DOUBLE SIDED



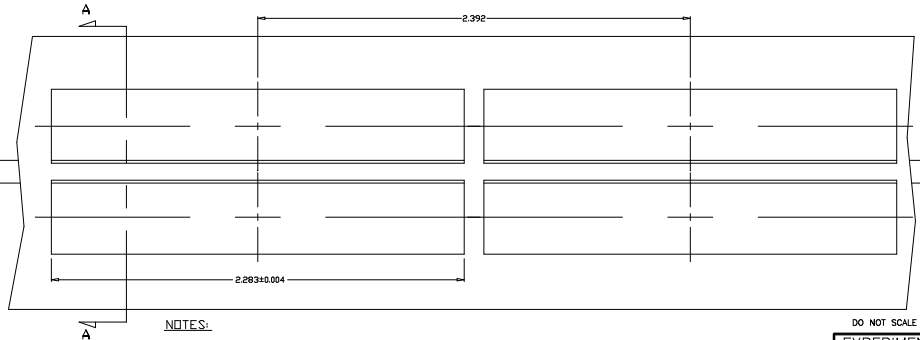
RECOMMENDED FOOTPRINT

SINGLE SIDED

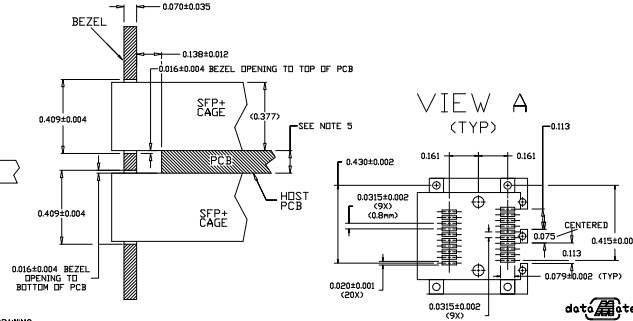


LTR.		ECN		REVISION AND CHANGE EFFECTIVITY DATE	DATE	APP'D.
				DESCRIPTION		

RECOMMENDED PANEL CUTOUT



SECTION A-A



- NOTES:**
- 1) DIMENSIONS ARE TO CENTER OF HOLES
 - 2) THRU HOLES, PLATING OPTIONAL
 - 3) PADS AND VIAS ARE CHASSIS GROUND
 - 4) TRACES ONLY NO COMPONENTS
 NO TRACES NO COMPONENTS (EXCEPT CHASSIS GROUND)
 - 5) PCB THICKNESS: 0.062" MIN FOR SINGLE SIDED, 0.125" MIN FOR DOUBLE SIDED

DO NOT SCALE DRAWING.

EXPERIMENTAL NO.:		DIVISION ASSIGNED: dataMate Division	
TOLERANCES UNLESS OTHERWISE SPECIFIED	MATERIAL: SEE NOTES	DRAWN BY: A. PRILLIS	DATE: 07/18/11
METRIC ± DEC. XX ± .010 ± XXX ± .005	FINISH: SEE NOTES	CHECKED BY: J. LLORENS	DATE: 07/18/11
ANGLES 1		ENGR. APPROVAL: B. SKEPNEK	DATE: 07/18/11
TOOLING DWG <input type="checkbox"/>		APPROVED BY: A. CHIAPPETTA	DATE: 07/18/11
PART DWG <input type="checkbox"/>		PART NO. CLASSIFICATION:	
BREAK SHARP EDGES REMOVE ALL BURRS		BETHODE ELECTRONICS, INC. TITLE SFP+ EMI 4 PORT CAGE (MULTI-CONTACT) PRESS FIT PINS, HEAT SINK BERYLLIUM COPPER GASKET SIZE: C CODE IDENT. DWG. NUMBER DM7060-4-B-H-X Rev. SCALE: DATE:	

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